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TITLE: NI-1230-8	DOCUMENT NO: 98ASA00120D REV: D	
	STANDARD: NON-JEDEC	
	SOT1794-1	22 FEB 2016



NOTES:

- 1.0 INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
- 2.0 CONTROLLING DIMENSION: INCH
- 3.0 DIMENSION H1 AND H2 ARE MEASURED .030 (0.762) AWAY FROM PACKAGE BODY.
H1 APPLIES TO PINS 2,3,6,7. H2 APPLIES TO PINS 1,4,5,8.
- 4.0 RECOMMENDED BOLT CENTER DIMENSION OF 1.52 (38.61) BASED ON M3 SCREW.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	1.615	1.625	41.02	41.28	N	1.218	1.242	30.94	31.55
B	.395	.405	10.03	10.29	Q	.120	.130	3.05	3.3
C	.150	.200	3.81	5.08	R	.365	.375	9.27	9.53
D	.455	.465	11.56	11.81	S	.365	.375	9.27	9.53
E	.062	.066	1.57	1.68	V1	1.320	1.330	33.53	33.78
F	.004	.007	0.10	0.18	U	.035	.045	0.89	1.14
G	1.400 BSC		35.56 BSC		W1	.225	.235	5.72	5.97
H1	.082	.090	2.08	2.29	W2	.431	.441	10.95	11.20
H2	.078	.094	1.98	2.39	W3	.491	.501	12.47	12.73
K	.117	.137	2.97	3.48	Y	1.390 BSC		35.31 BSC	
L	.540 BSC		13.72 BSC		Z	---	R.020	---	R0.51
M	1.219	1.241	30.96	31.52	aaa	.013		0.33	
					bbb	.010		0.25	
					ccc	.020		0.51	

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